

PATENT

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February 11, 2002 S. Jansen
Date Stephanie Jansen

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	: Jason B. Elledge	Attorney Docket No.:	500188.02
Serial No.	: 09/616,794	Group Art Unit	: 3723
Filed	: July 14, 2000	Examiner	: Willie Berry, Jr.
Title	: APPARATUS FOR IN-SITU OPTICAL ENDPOINTING ON WEB-FORMAT PLANARIZING MACHINES IN MECHANICAL OR CHEMICAL-MECHANICAL PLANARIZATION OF MICROELECTRONIC-DEVICE SUBSTRATE ASSEMBLIES AND METHODS FOR MAKING AND USING SAME		

Commissioner of Patents
Washington, DC 20231

AMENDMENT

Sir:

Applicant acknowledges receipt of the Office Action dated December 31, 2001.

In the Claims:

Please cancel claims 41, 42, 44, and 45, amend claims 40 and 43, and add new claims 46-79 as follows:

40. (Amended) A method of endpointing mechanical or chemical-mechanical planarization processing of microelectronic-device substrate assemblies, comprising:

initially passing a light beam from an illumination site in a table through a first optically transmissive view site located at first area within an elongated slot in a polishing pad to at least periodically impinge a first substrate assembly with the light beam and optically sense a surface condition of the first substrate assembly;